

Substitute for Form 1449 A & B/PTO

DEC 23 2003

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Complete if Known

Application Number	10/660,730
Confirmation Number	4923
Filing Date	September 12, 2003
First Named Inventor	Abraham GROSS et al.
Art Unit	4722-1725
Examiner Name	Unknown
Attorney Docket Number	Q77482

Sheet

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of

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Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
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SMH		US 60/387,911		Jun, 2002	Gross et al.
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SMH		WO	0064623		Nov, 2000	GSI Lumonics Inc.	
SMH		EP	1224999		Apr, 2001	Sumitomo Heavy Industries	
SMH		WO	03071344		Aug 28, 2003	Orbotech Ltd.	

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation ⁶
SMH		Mignardi et al. "The Digital Micromirror Device - a Micro-Optical Electromechanical Device for Display Applications", MEMS and MOEMS Technology and Applications, SPIE Press, 2000	
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Signature

S. Heinrich

Date
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Aug. 25, 2005

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